1-535541-4 - ACTIVE

AMPMODU | Modu Connector System

TE Internal #: 1-535541-4 PCB Mount Receptacle, Vertical, Board-to-Board, 16 Position, 2.54 mm [.1 in] Centerline, Gold (Au), Through Hole - Solder, Modu Connector System

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PCB Connector Type: PCB Mount Receptacle

PCB Mount Orientation: Vertical

Connector System: Board-to-Board

Number of Positions: **16**

Number of Rows: 1

Features

Product Type Features

Applied PressureStandardPCB Connector TypePCB Mount ReceptacleConnector SystemBoard-to-Board



Sealable	No
Connector & Contact Terminates To	Printed Circuit Board
Connector Product Type	Connector Assembly
Configuration Features	
Board-to-Board Configuration	Parallel
Stackable	Yes
PCB Mount Orientation	Vertical
Number of Positions	16
Number of Rows	1
Electrical Characteristics	
Operating Voltage	333 VAC
Insulation Resistance	5000 MΩ
Dielectric Withstanding Voltage (Max)	750 VAC
Body Features	
Connector Profile	Standard

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Primary Product Color	Black
Contact Features	
Contact Mating Area Plating Material Thickness	.762 μm[30 μin]
Mating Square Post Dimension	.64 mm[.025 in]
PCB Contact Termination Area Plating Material Thickness	3.81 – 50 µm
Contact Shape & Form	Square
Contact Layout	Inline
Contact Protection Type	Closed Entry Housing
Contact Base Material	Phosphor Bronze
PCB Contact Termination Area Plating Material	Tin-Lead
Contact Mating Area Plating Material	Gold (Au)
Contact Type	Socket
Contact Current Rating (Max)	3 A
Termination Features	
Rectangular Termination Post & Tail Width	.7 mm[.028 in]
Rectangular Termination Post & Tail Thickness	.2 mm[.008 in]
Termination Post & Tail Length	3.18 mm[.125 in]
Termination Method to PCB	Through Hole - Solder

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Mechanical Attachment

PCB Mount Retention	Without
PCB Mount Alignment	Without
Connector Mounting Type	Board Mount
Mating Alignment	Without
Housing Features	
Mating Entry Location	Тор
Housing Material	Polyester - GF
Centerline (Pitch)	2.54 mm[.1 in]
Dimensions	
Stack Height	9.02 mm[.355 in]
PCB Thickness (Recommended)	1.4 – 2.4 mm[.055 – .094 in]
Connector Height	3.56 mm[.14 in]
Usage Conditions	

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Housing Temperature Rating	Standard	
Operating Temperature Range	-65 – 125 °C[-85 – 257 °F]	
Operation/Application		
Solder Process Feature	Board Standoff	
Circuit Application	Signal	
Industry Standards		
Compatible With Approved Standards Products	CSA LR7189, UL E28476	
UL Flammability Rating	UL 94V-0	
Packaging Features		
Packaging Quantity	14	
Packaging Method	Box, Tube	
Product Compliance For compliance documentation, visit the product page on TE.com>		
EU RoHS Directive 2011/65/EU	Not Compliant	
EU ELV Directive 2000/53/EC	Compliant with Exemptions	
China RoHS 2 Directive MIIT Order No 32, 2016	Restricted Materials Above Threshold	

EU REACH Regulation (EC) No. 1907/2006	Current ECHA Candidate List: JUNE 2024 (241) Candidate List Declared Against: JUNE 2024 (241) SVHC > Threshold:		
	Pb (13% in Component Part) Article Safe Usage Statements: Do not eat, drink or smoke when using this product. Wash thoroughly after handling. Recycle if possible and dispose of the article by following all applicable governmental regulations relevant to your geographic location.		
Halogen Content	Not Low Halogen - contains Br or Cl > 900 ppm.		
Solder Process Capability	Wave solder capable to 240°C		
Product Compliance Disclaimer			

This information is provided based on reasonable inquiry of our suppliers and represents our current actual knowledge based on the information they provided. This information is subject to change. The part numbers that TE has identified as EU RoHS compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, mercury, PBB, PBDE, DBP, BBP, DEHP, DIBP, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2011/65/EU (RoHS2). Finished electrical and electronic equipment products will be CE marked as required by Directive 2011/65/EU. Components may not be CE marked. Additionally, the part numbers that TE has identified as EU ELV compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, and mercury, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2000/53/EC (ELV). Regarding the REACH Regulation, the information TE provides on SVHC in articles for this part number is based on the latest European Chemicals Agency (ECHA) 'Guidance on requirements for substances in articles' posted at this URL: https://echa.europa.eu/guidance-documents/guidance-on-reach

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Compatible Parts

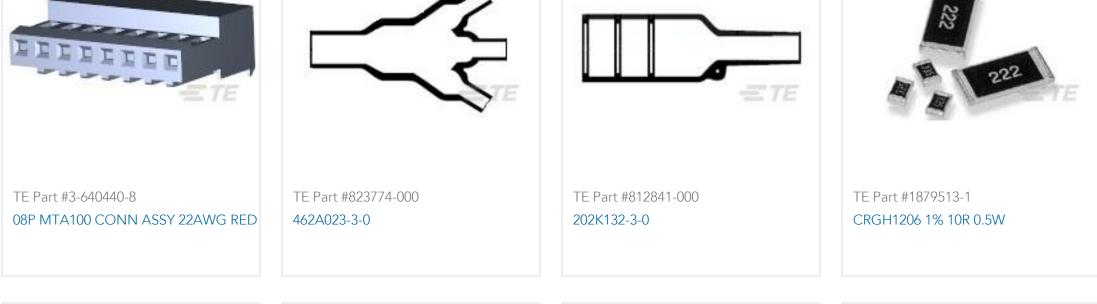


Also in the Series Modu Connector System

Board-to-Board Headers & Receptacles(814)	Board-to-Board Jumpers & Shunts(5)	Connector Hardware(4)	PCB Headers & Receptacles(814)

Customers Also Bought







PCB Mount Receptacle, Vertical, Board-to-Board, 16 Position, 2.54 mm [.1 in] Centerline, Gold (Au), Through Hole - Solder, Modu Connector System





Documents

Product Drawings 16 MODIV VRT SR CE 100/115

English

CAD Files

3D PDF

English

Customer View Model

ENG_CVM_1-535541-4_N.3d_igs.zip

English

Customer View Model

ENG_CVM_1-535541-4_N.3d_stp.zip

English

Customer View Model

ENG_CVM_1-535541-4_N.2d_dxf.zip

English

By downloading the CAD file I accept and agree to the **Terms and Conditions** of use.

Product Specifications Application Specification

English